


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/17/9976	
1.3 Title of PCN	Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for selected products in LQFP packages	
1.4 Product Category	Listed LQFP 32 7x7, LQFP 44 10x10, LQFP 48 7x7 & LQFP 64 10x10 packaged products	
1.5 Issue date	2017-02-27	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ASHLEY MCGAHA
2.1.2 Phone	+1 7814028545
2.1.3 Email	ashley.mcgaha@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Daniel COLONNA
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer...)	Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

4. Description of change

	Old	New
4.1 Description	Current locations : Stats ChipPAC Shanghai China (SCC), Amkor ATP Philippines and ST Muar Malaysia	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. Amkor ATP Philippines and ST Muar Malaysia locations remain. See more information on PCN 9976 – Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change on form fit function. Lead color and surface finish may change depending on leadfinishing.	

5. Reason / motivation for change

5.1 Motivation	Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only LQFP packaged products listed.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability is described in PCN9976_Additional information attached document
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7. Timing / schedule

7.1 Date of qualification results	2017-05-19
7.2 Intended start of delivery	2017-06-19
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	9976 PCN9976_PCN10011_RERMCD1621- LQFP JSCC- MCD QA reliability plan.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-02-27
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9. Attachments (additional documentations)

<p>9976 Public product.pdf 9976 PCN9976_Additional information.pdf 9976 PCN9976_PCN10011_RERMCD1621- LQFP JSCC- MCD QA reliability plan.pdf</p>

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F100RBT6B	
	STM32F101C8T6	
	STM32F103RCT6	
	STM32F103RGT6	
	STM32F405RGT6	

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